

ABSTRACT OF THE DISCLOSURE

A reticle for manufacturing a semiconductor device. The reticle includes cutouts that permit material deposited through the reticle and onto a surface of a semiconductor device being
5 manufactured to form the shape of the cutouts. Shapes defined in the cutouts and produced on the semiconductor device include first and second topographic structures, where the first are made up of conductive lead lines, and the second made up of fill patterns such that the top surfaces of the second topographic structures are generally coplanar with the top surfaces of the first topographic structures. The first and second topographic structures can be arranged in a
10 generally repeating array on the substrate.